

SOT1950-1

WLCSP72, wafer level chip-scale package, 72 bumps, 4.46 mm x 3.96 mm x 0.53 mm body

5 October 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP72
Package type industry code	WLCSP72
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	5-10-2017
Manufacturer package code	SOT1950-1

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.43	-	4.46	4.49	mm
E	package width	3.93	-	3.96	3.99	mm
A	seated height	0.49	-	0.53	0.57	mm
A ₂	package height	0.27	-	0.3	0.33	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	72	-	A/A



2. Package outline

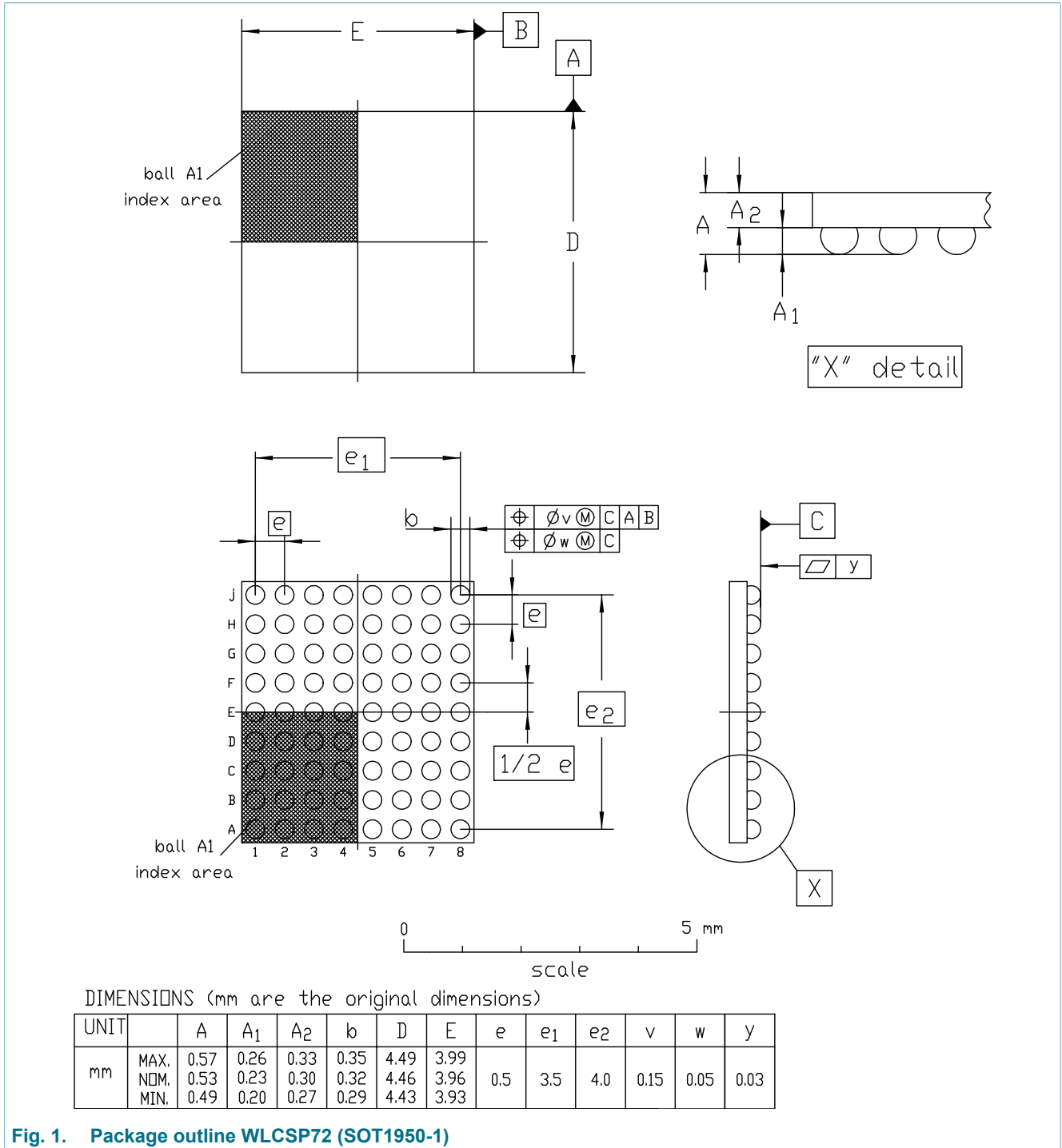


Fig. 1. Package outline WLCSP72 (SOT1950-1)

3. Legal information

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